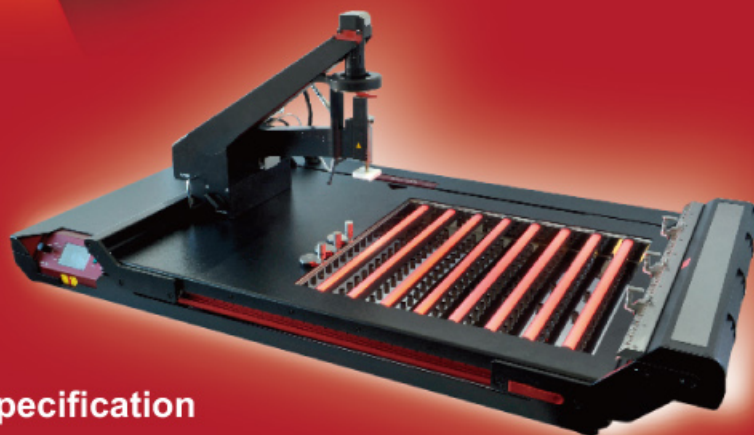


BGA Engine MaFi-668

The most powerful BGA rework system

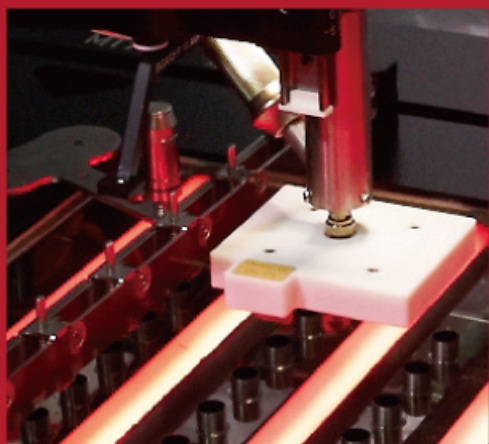


獨特的**底部支撐架**，能夠完美的記憶PCB底部高低起伏之高度差，如同記憶枕般提供PCB完美的支撐



Specification

Power Input	230 V / 50 Hz 25 A
Pressure Input	5.5~8 Bar
Hot air power output	10~250 W / 40 V
Hot air volume	2.0~35 L / Min
Hot air temp	150~400°C ± 1%
Underheater power	1200~5000 W
Underheater size	420 x 450 mm
PCB size	500 x 600 mm
CCD camera resolution	1944 x 2595 pixel
Auto placement stroke	X-Y-Z / 75-75-40 mm
Auto placement angle	±10 °
CCD lighting	Ring type LED
PCB clipping	smart clip
PCB supporting	Flex Fix pin bar supporter (optional)
Weight	approx. 70 Kg
Communication Link	USB
Program software	Easy Solder
Thermo sensors	2 + 4
Hot air nozzle	CSP 4 pieces (covering all specs) optional
(all nozzles are optional)	BGA15 / 16 / 17 / 19 / 21 / 23 / 25 / 27 / 29 / 31 / 32 / 33 / 35 / 37.5 / 40 / 40.5 / 45 / 46mm... Socket 478B / 775 / 1207 / 1165 / 1366 / 1567



功能強大的全新**雙模底部加熱器**，快速及時且非常均勻的提供底部預熱能量，PCB受熱就像在迴焊爐一般，保持最低PCB板彎扭曲量